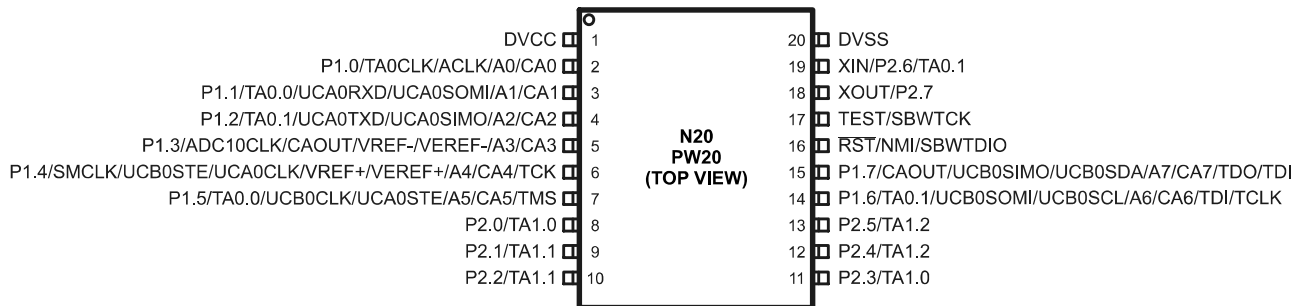


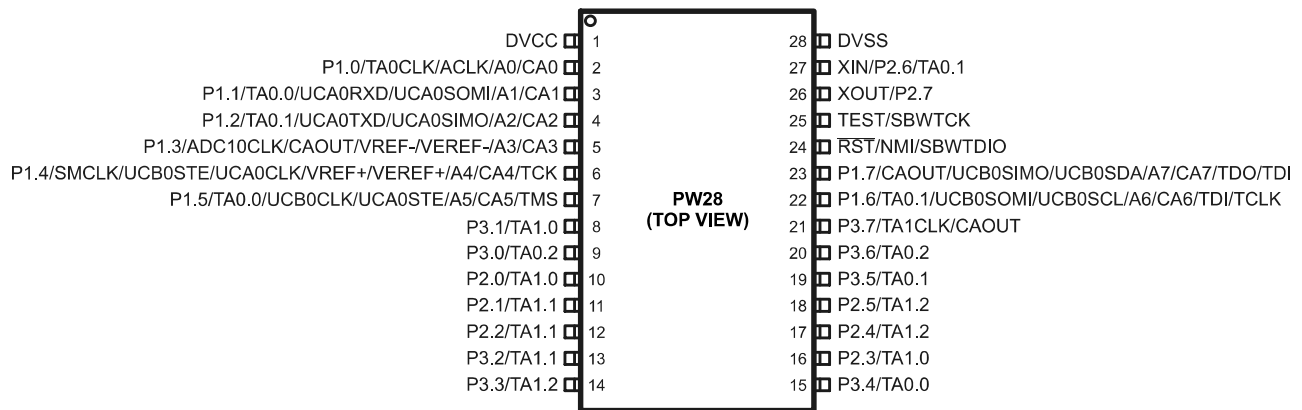
## Device Pinout, MSP430G2x13 and MSP430G2x53, 20-Pin Devices, TSSOP and PDIP



NOTE: ADC10 is available on MSP430G2x53 devices only.

NOTE: The pulldown resistors of port P3 should be enabled by setting P3REN.x = 1.

## Device Pinout, MSP430G2x13 and MSP430G2x53, 28-Pin Devices, TSSOP

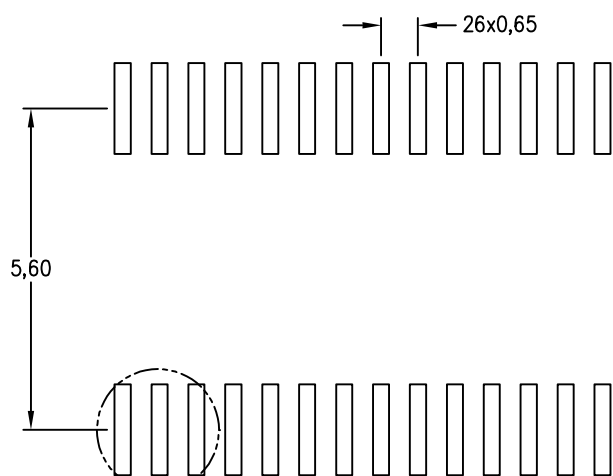


NOTE: ADC10 is available on MSP430G2x53 devices only.

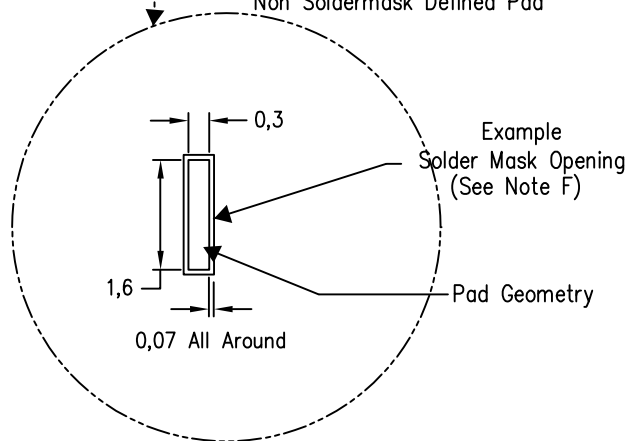
PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE

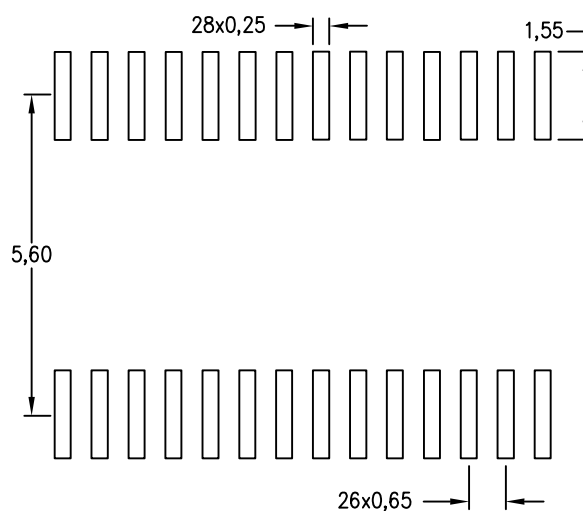
Example Board Layout



Example  
Non Soldermask Defined Pad



Stencil Openings  
Based on a stencil thickness  
of .127mm (.005inch).



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NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.